

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 1-1932000-0

Double Data Rate (DDR) 3, Board-to-Board, 240 Position, Through Hole - Solder, Vertical Module Orientation, DDR3 DIMM, DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM Sockets



DRAM Type: Double Data Rate (DDR) 3

Connector System: Board-to-Board

Number of Positions: 240

Termination Method to PCB: Through Hole - Solder

Module Orientation: Vertical

[All DDR3 DIMM Sockets \(13\)](#)

Features

Product Type Features

|                                   |                          |
|-----------------------------------|--------------------------|
| Connector & Contact Terminates To | Printed Circuit Board    |
| DRAM Type                         | Double Data Rate (DDR) 3 |
| Connector System                  | Board-to-Board           |

Configuration Features

|                     |          |
|---------------------|----------|
| Number of Keys      | 1        |
| Number of Bays      | 2        |
| Number of Rows      | 2        |
| Number of Positions | 240      |
| Module Orientation  | Vertical |

Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.5 V |
|--------------|-------|

Body Features

|  |  |
|--|--|
|  |  |
|--|--|



|                                |                        |
|--------------------------------|------------------------|
| Retention Post Location        | Center                 |
| Latch Color                    | Natural                |
| Latch Material                 | Thermoplastic          |
| PCB Retention Feature Material | Brass                  |
| Ejector Material Color         | Natural                |
| Module Key Type                | Offset Left            |
| Ejector Location               | Both Ends              |
| Ejector Material               | High Temperature Nylon |
| Ejector Type                   | Standard               |

Contact Features

|                                                         |                 |
|---------------------------------------------------------|-----------------|
| Contact Underplating Material                           | Nickel          |
| Socket Style                                            | DIMM            |
| Contact Mating Area Plating Material Thickness          | .38 µm[15 µin]  |
| PCB Contact Termination Area Plating Material Thickness | 3 µm[118.1 µin] |
| Contact Mating Area Plating Material                    | Gold (Au)       |
| Memory Socket Type                                      | Memory Card     |
| Contact Base Material                                   | Copper Alloy    |
| PCB Contact Termination Area Plating Material           | Tin             |
| Contact Current Rating (Max)                            | .75 A           |

Termination Features

|                                |                       |
|--------------------------------|-----------------------|
| Insertion Style                | Direct Insert         |
| Termination Post & Tail Length | 2.67 mm[.105 in]      |
| Termination Method to PCB      | Through Hole - Solder |

Mechanical Attachment

|                          |                     |
|--------------------------|---------------------|
| Connector Mounting Type  | Board Mount         |
| PCB Mount Retention      | With                |
| Mount Angle              | Vertical            |
| PCB Mount Retention Type | Retention Clip/Post |
| Mating Alignment Type    | Center              |
| Mating Alignment         | With                |

Housing Features

|                  |                        |
|------------------|------------------------|
| Housing Color    | Black                  |
| Housing Material | High Temperature Nylon |



|                    |               |
|--------------------|---------------|
| Centerline (Pitch) | 1 mm[.039 in] |
|--------------------|---------------|

Dimensions

|                                |                 |
|--------------------------------|-----------------|
| Center Retention Hole Diameter | 1.8 mm[.07 in]  |
| Profile Height from PCB        | 23.1 mm[.9 in]  |
| Row-to-Row Spacing             | 1.9 mm[.075 in] |

Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 155 °C[-67 – 311 °F] |
|-----------------------------|----------------------------|

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

|                    |      |
|--------------------|------|
| Packaging Quantity | 50   |
| Packaging Method   | Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                       |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2025 (250)<br>Candidate List Declared Against: JUNE 2022 (224)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                  |
| Solder Process Capability                     | Wave solder capable to 260°C                                                                                                    |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits





as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 2-2308107-7  
DDR4 DIMM 288 PIN TH TYPE

Also in the Series | DDR3 DIMM



DIMM Sockets(9)

Also in the Series | DDR3 SO DIMM



DIMM Sockets(9)



SO DIMM Sockets(3)

Customers Also Bought



TE Part #CAT-D9934-A75  
Contact: Component To Wire; 15A, 28-14 wire size



TE Part #1-178288-6  
DYNAMIC D3100 REC HSG 6P



TE Part #350432-4  
09P UMNL PIN HDR ASSY NATL LF



TE Part #1761008-3  
SFP 1X4 CAGE & LIGHT PIPE KIT



TE Part #2227666-3  
ZQSFP+ STACKED, 2X1, THRU BEZEL  
W SPRING



TE Part #2318579-1  
RCPT CONN R/A SMT 76 POSN QSFP-DD

Documents

Product Drawings

VERTICAL DDR3 DIMM, 240 POSITION

English

CAD Files

Customer View Model

ENG\_CVM\_CVM\_1-1932000-0\_F.2d\_dxf.zip

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1-1932000-0\_F.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-1932000-0\_F.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

6-1773457-3\_DDR3\_DIMM\_SOCKETS

Product Specifications

Product Specification

English

Agency Approvals

Agency Approval Document

English